

# **SPECIFICATIONS**

|                 |                          |
|-----------------|--------------------------|
| <b>MODEL</b>    | <b>Infrared LAMP LED</b> |
| <b>PART NO.</b> | <b>LI520C</b>            |

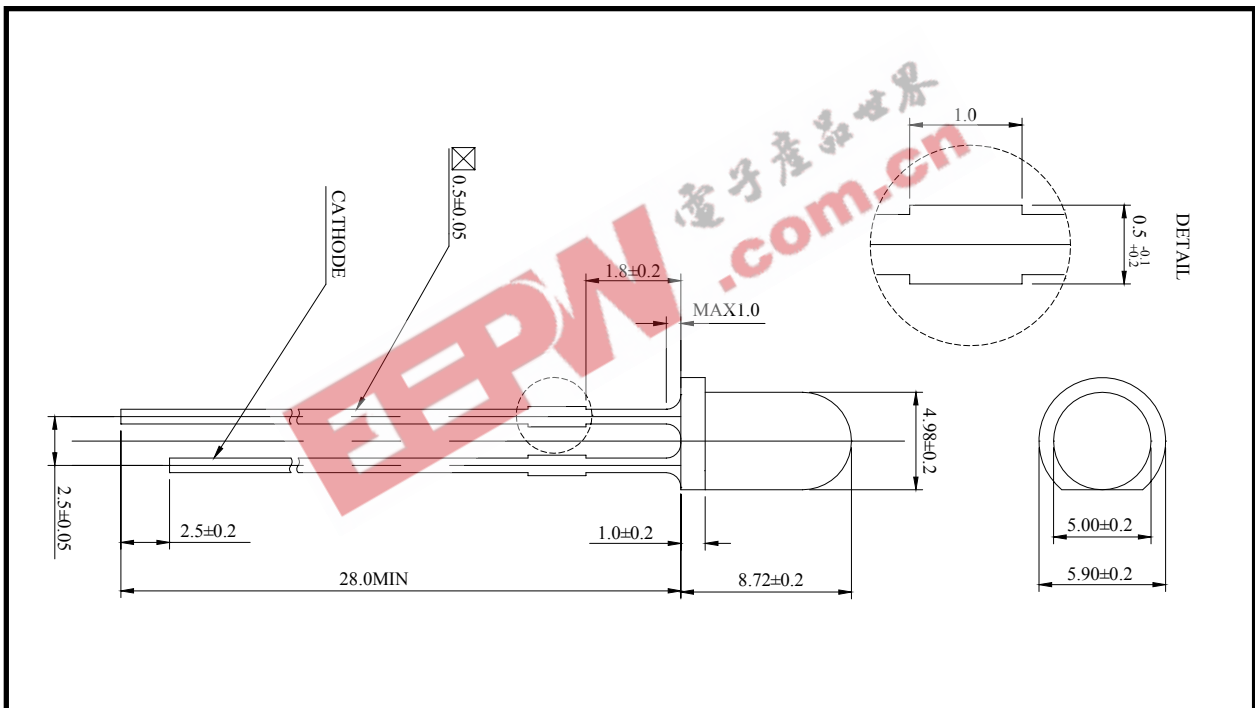
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## 1. Devices

| Part Number | Lens        |              | Source      |          |
|-------------|-------------|--------------|-------------|----------|
|             | Color       | Diffusion    | Dice Source | Color    |
| LI520C      | Blue -Risen | Non-Diffused | GaAlAs/GaAs | Infrared |

## 2. Outline Dimensions



- Notes : 1. All dimensions are in millimeters.  
 2. Protruded epoxy is 1.0mm maximum.



### 3. Absolute Maximum Ratings (at $T_a = 25^\circ\text{C}$ )

| Item                       | Symbol        | Value   | Unit             |
|----------------------------|---------------|---|------------------|
| DC Forward Current         | $I_F$         | 100   | mA               |
| Forward Peak Pulse Current | $I_{FM}^{*1}$ | 1000  | mA               |
| Reverse Voltage            | $V_R$         | 5   | V                |
| Power Dissipation          | $P_D$         | 150   | mW               |
| Operating Temperature      | $T_{opr}$     | -20 ~ +80                                       | $^\circ\text{C}$ |
| Storage Temperature        | $T_{stg}$     | -30 ~ +100                                      | $^\circ\text{C}$ |
| Solder Temperature         | $T_S$         | 260 $^\circ\text{C}$ for 5 second <sup>*2</sup> | $^\circ\text{C}$ |

Notes : \*1.  $t \leq 0.01\text{ms}$ ,  $D = 1/100$

\*2. 3mm bellow seating plane



#### 4. Electro-Optical Characteristics (at $I_F = 100\text{mA}$ , $T_a = 25^\circ\text{C}$ )

| Item                                    | Symbol          | Value |      |      | Unit          |
|---|-----------------|-------|------|------|---------------|
|   |                 | Min.  | Typ. | Max. |               |
| Radiant Intensity                       | $I_e$           | 30    | 65   | 130  | mW/sr         |
| Peak Wavelength                         | $\lambda_p$     | -     | 940  | -    | nm            |
| Spectrum Radiation Bandwidth            | $\Delta\lambda$ | -     | 50   | -    | nm            |
| Forward Voltage                         | $V_F$           | -     | 1.2  | 1.55 | V             |
| View Angle                              | $2\theta_{1/2}$ | 24    |      |      | deg.          |
| Reverse Current (at $V_R = 5\text{V}$ ) | $I_R$           | 10    |      |      | $\mu\text{A}$ |

Note : 1. Radiant Intensity Tolerance  $\pm 10\%$



## 5. RELIABILITY TESTS

| Item                           | Condition   | Note       | Failures |
|--------------------------------|---|------------|----------|
| Life Test                      | $T_a = RT, I_F = 100mA$   | 1000 hrs   | 0/22     |
| High Temperature Operating     | $T_a = 85^{\circ}C, I_F = 25mA$   | 1000 hrs   | 0/22     |
| Low Temperature Operating      | $T_a = -40^{\circ}C, I_F = 100mA$   | 1000 hrs   | 0/22     |
| Thermal Shock                  | $T_a = -30^{\circ}C \sim +100^{\circ}$<br>(Transfer time : 5sec , 1 Cycle =1hr) | 100 cycles | 0/22     |
| Temperature Cycle              | $T_a = -20^{\circ}C \sim +80^{\circ}C$<br>(Transfer time : 5min , 1 Cycle =1hr) | 100 cycles | 0/22     |
| Resistance to soldering Heat   | $T_s = 260 \pm 5^{\circ}C, t = 10 \pm 1 \text{ sec}$                            | 1 time     | 0/22     |
| ESD<br>(Human Body Model)      | 1 kV, 1.5 k $\Omega$ ; 100 pF   | 1 time     | 0/22     |
| High Temperature Storage       | $T_a = 100^{\circ}C$  | 1000 hrs   | 0/22     |
| Low Temperature Storage        | $T_a = -30^{\circ}C$  | 1000 hrs   | 0/22     |
| Temperature Humidity Storage   | $T_a = +85^{\circ}C, RH=85\%$   | 1000hrs    | 0/22     |
| Temperature Humidity Operating | $T_a = +85^{\circ}C, RH=85\%$<br>$I_F = 25mA$                                   | 100hrs     | 0/22     |

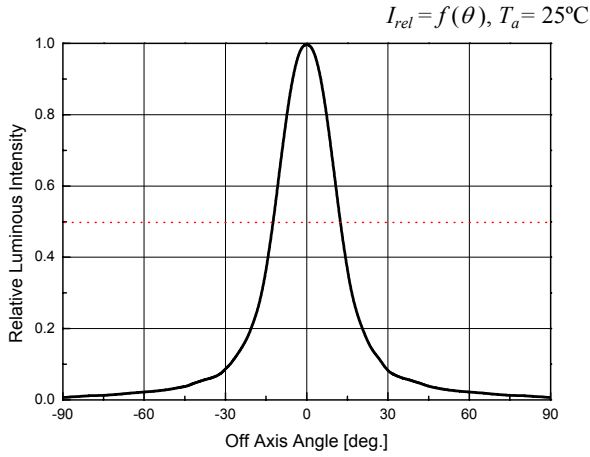
### < Judging Criteria For Reliability Tests >

|                |                        |
|----------------|------------------------|
| V <sub>F</sub> | USL <sup>1</sup> X 1.2 |
| I <sub>R</sub> | USL X 2.0              |
| I <sub>V</sub> | LSL <sup>2</sup> X 0.5 |

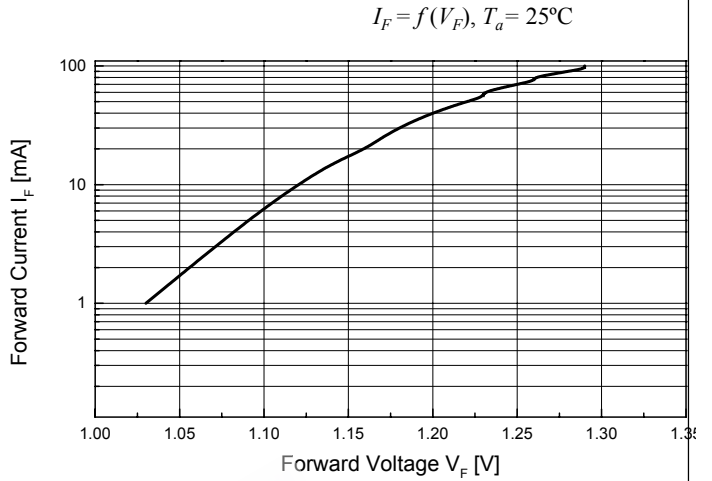
Notes : 1.USL : Upper Standard Level      2.LSL : Lower Standard Level.



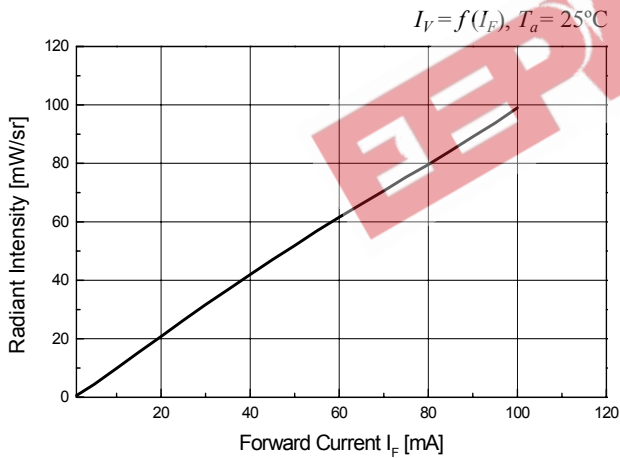
## 6. Characteristic Diagrams



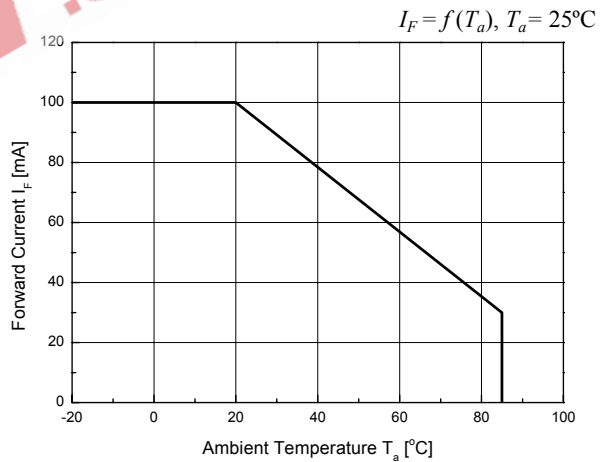
Off Axis Angle vs. Relative Radiant Intensity



Forward Voltage vs. Forward Current



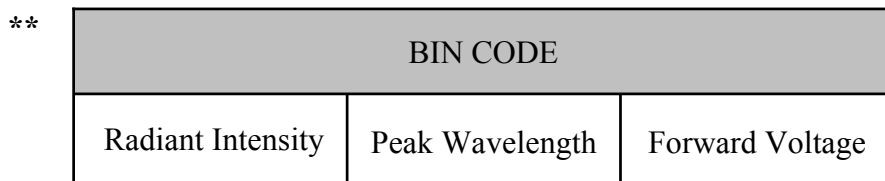
Forward Current vs. Radiant Intensity



Ambient Temperature vs. Forward Current



## 7. Bin Code Description



| Radiant Intensity ( $I_e$ )<br>@ $I_F = 100\text{mA}$ |      |      |
|---|------|------|
| BIN CODE  | Min. | Max. |
| A   | 30   | 55   |
| B   | 55   | 65   |
| C   | 65   | 70   |
| D   | 70   | 130  |

| Dominant Wavelength (nm)<br>@ $I_F = 100\text{mA}$ |     |
|--|-----|
| 1  | 940 |

| Forward Voltage (V)<br>@ $I_F = 100\text{mA}$ |      |      |
|---|------|------|
| BIN CODE                                      | Min. | Max. |
| 1   | 1.2  | 1.55 |

\*\* Note : Binning range can be changed by customer's requirement.



## 8. PACKING

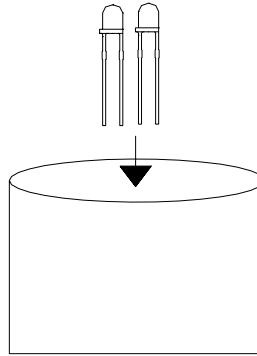
### 1) Bulk Packing

#### (1) Antistatic poly vinyl bag apply

Poly bag:

5φ Lamp Series : 500pcs

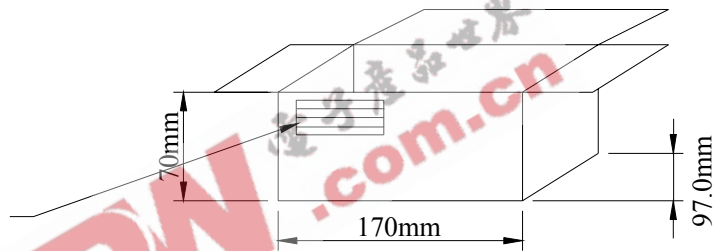
3φ Lamp Series : 500pcs



#### (2) Inner box structure

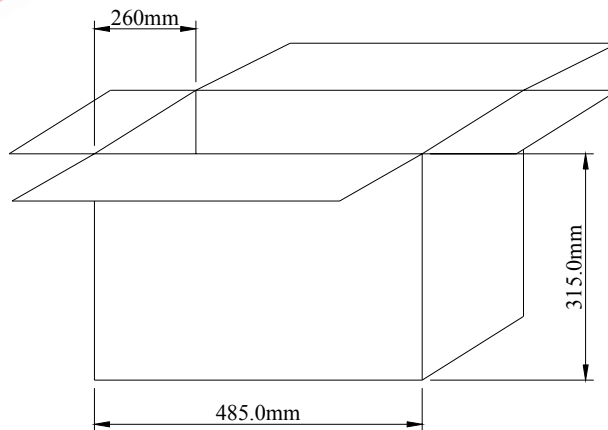
Box : 2 poly bags

|   |  |         |
|---|--|---------|
|   |  | P/O No. |
| Lot No.   |  |         |
| SEOUL SEMICONDUCTOR CO.,LTD<br>TEL : (02) 3281-6269 |  |         |



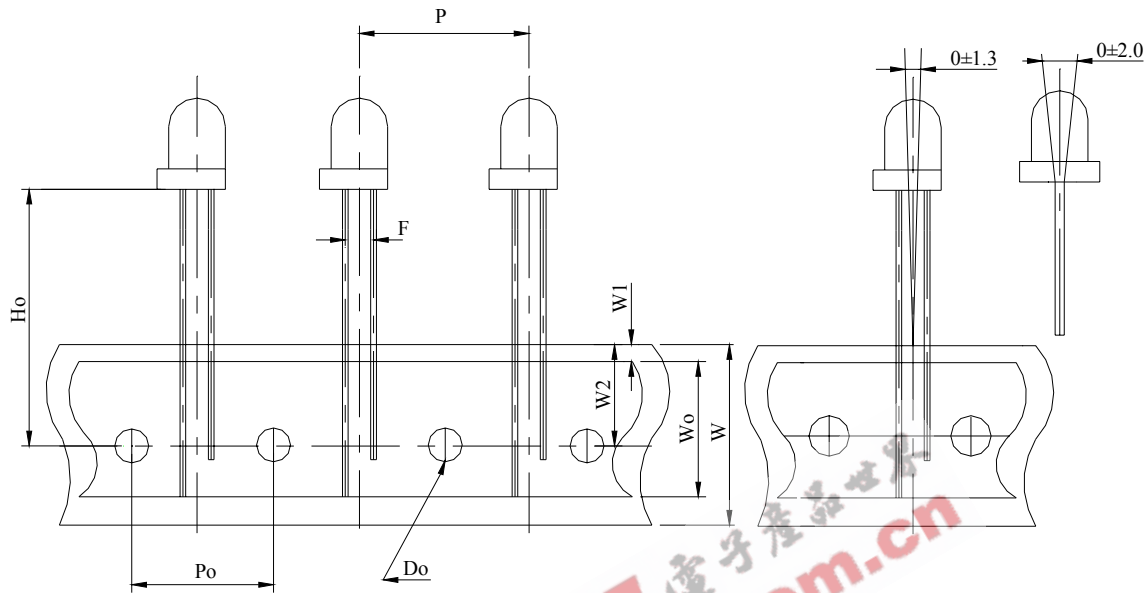
#### (3) Outer box structure

Box : 27 boxes



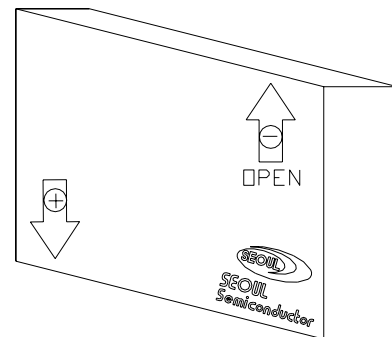


## 2) Tapping Outline Dimensions



| Package Dimensions (unit : mm) |                                      |    |          |
|--------------------------------|--------------------------------------|----|----------|
| Ho*                            |                                      | P  | 12.7±0.5 |
| W                              | 18.0 <sup>+1.0</sup> <sub>-0.5</sub> | Po | 12.7±0.3 |
| W0                             | 13.0±0.3                             | F  | 2.54±0.5 |
| W1                             | 1.0±0.5                              | Do | φ4.0±0.5 |
| W2                             | 9.0±0.5                              |    |          |

\* Remark : Ho - users define.



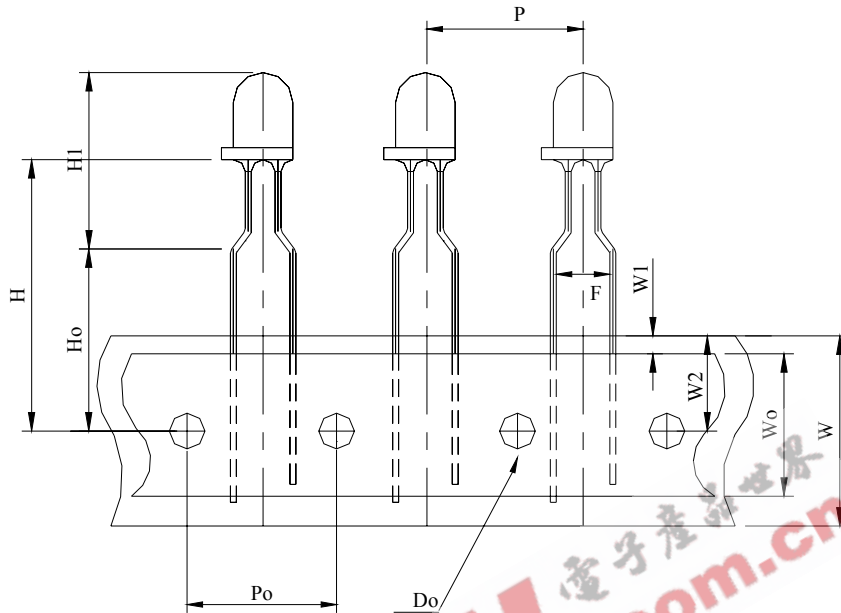
1 Box contain quantity.

\* 3φ Lamp Series : 3000pcs

\* 5φ Lamp Series : 2000pcs

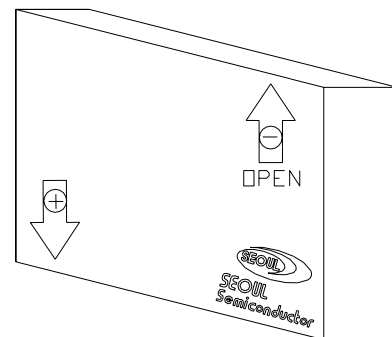


### 3) Forming Outline Dimensions



| Package Dimensions (unit : mm) |                                      |    |          |
|--------------------------------|--------------------------------------|----|----------|
| H *                            |                                      | W2 | 9.0±0.5  |
| Ho *                           |                                      | P  | 12.7±0.5 |
| H1 *                           |                                      | Po | 12.7±0.3 |
| W                              | 18.0 <sup>+1.0</sup> <sub>-0.5</sub> | F  | 5.0±0.5  |
| Wo                             | 13.0±0.3                             | Do | φ4.0±0.5 |
| W1                             | 1.0±0.5                              |    |          |

\* Remark : H / Ho / H1- users define.



1 Box contain quantity.

\* 3φ Lamp Series : 2000pcs

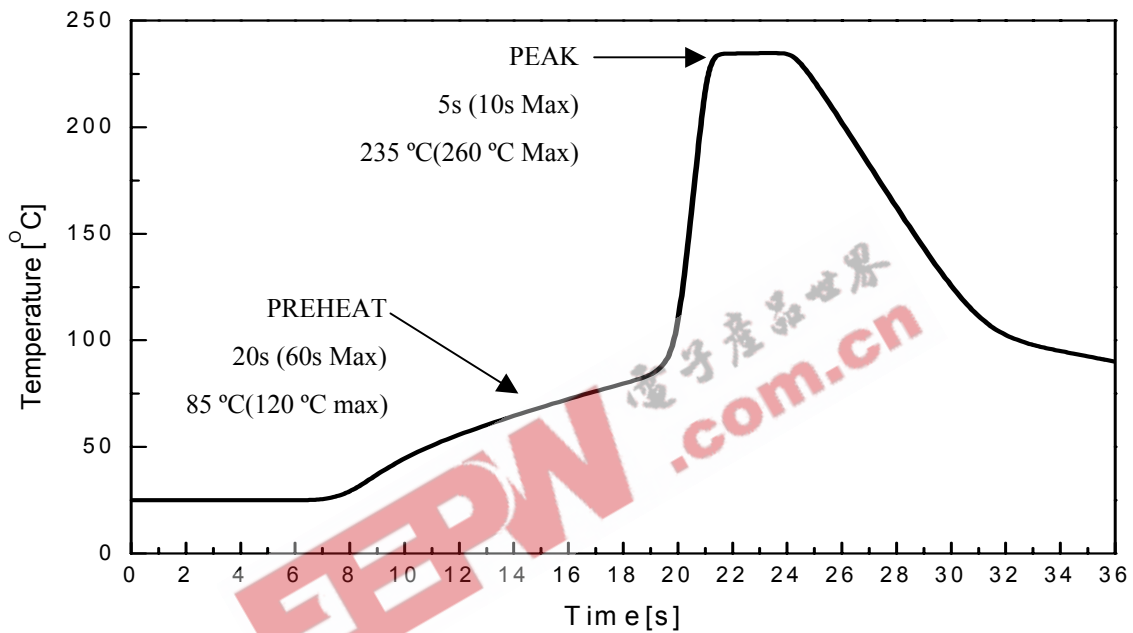
\* 5φ Lamp Series : 1500pcs



## 9. SOLDERING PROFILE

### 1) Wave Soldering Conditions / Profile

- Preliminary heating to be at 85°C(120 °C max) for 20 seconds(60 seconds max).
- Soldering heat to be at 235 °C (260°C max) for 5 seconds (10 seconds max.)
- Soak time above 200 °C is 5 seconds



### 2) Hand Soldering conditions

- Not more than 5 seconds at max. 300°C, under Soldering iron.

Note : In case the soldered products are reused in soldering process, we don't guarantee the products.



## 10. PART NUMBERING SYSTEM

|   |   |   |   |   |   |   |   |   |   |   |   |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 |   | A | B | C |
| L | * | * | * | * | * | * | * | - | * | * | * |

1) Lamp LED initial

2) Color

U: Ultra Violet,                      B : Blue (460~490),                      C : Cyan (490~510),  
 T : True Green (510~540), G : Yellow-Green (540~580)  
 Y : Yellow (580~600)              O : Orange (600~620)              R : Red (620~700)  
 W : White                                  M : Warm                                  I : Infrared

3) If the products have 2 or 3chips

GR : Green + Red ( according to wavelength), FL : Full color

4) Outline type

1 : 3x2(square),      2 : 5x2(square),      3 : Phi3,      5 : Phi 5 ,  
 6 : 3Phi Oval,      7 : 5Phi Oval

5) Half angle

1: ~14°, 2: 15~24°, 3: 25~34°, 4: 35~44°, 5 : 45~54°... 0 : more than 100°

6) 1<sup>st</sup> Development according to a chip

7) 2<sup>nd</sup> Development (other material)

D : diffused C : colored Z : zener chip attached

8) Stand off type

A, B, C : Bin cord description A: IV, B: WD C: VF



## 11. PRECAUTION FOR USE

- 1) In order to avoid the absorption of moisture, it is recommended to store in the dry box (or desiccators) with a desiccant .
- 2) In case of more than 1 week passed after opening or change color of indicator on desiccant components shall be dried 10-12Hr, at  $60\pm 5^{\circ}\text{C}$ .
- 3) In case of supposed the components is humid, shall be dried dip-solder just before, 12Hr at  $80\pm 5^{\circ}\text{C}$  or 10Hr at  $100\pm 5^{\circ}\text{C}$ .
- 4) Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temp. after soldering.
- 5) Quick cooling shall not be avoid.
- 6) Components shall not be mounted on warped direction of PCB.
- 7) Anti radioactive ray design is not considered for the products listed here in.
- 8) This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When washing is required, IPA should be used.
- 9) When the LEDs are illuminating, operating current should be decided after considering the ambient maximum temperature.
- 10) LEDs must be stored to maintain a clean atmosphere. If the LEDs are stored for 3 months or more after being shipped from SSC, a sealed container with a nitrogen atmosphere should be used for storage.
- 11) The LEDs must be soldered within seven days after opening the moisture-proof packing.
- 12) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.
- 13) The appearance and specifications of the product may be modified for improvement without notice.

